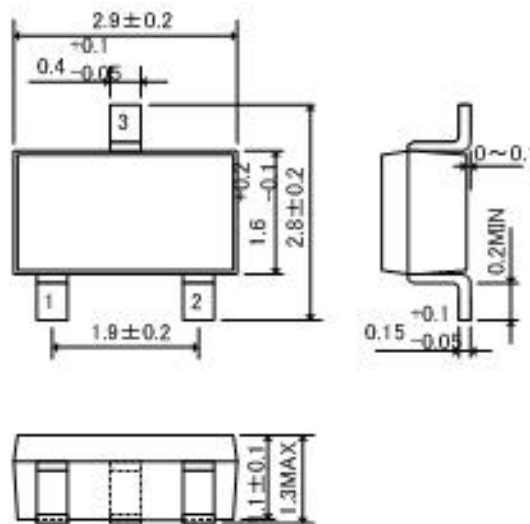


Packaging Information / Reference Pattern Layout Dimensions

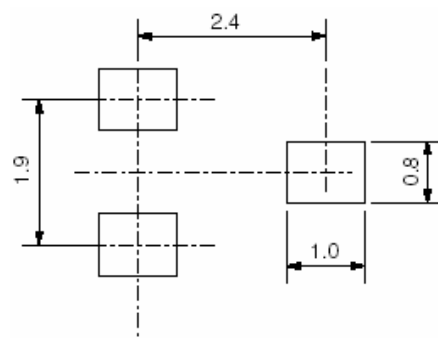
● SOT-23

Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

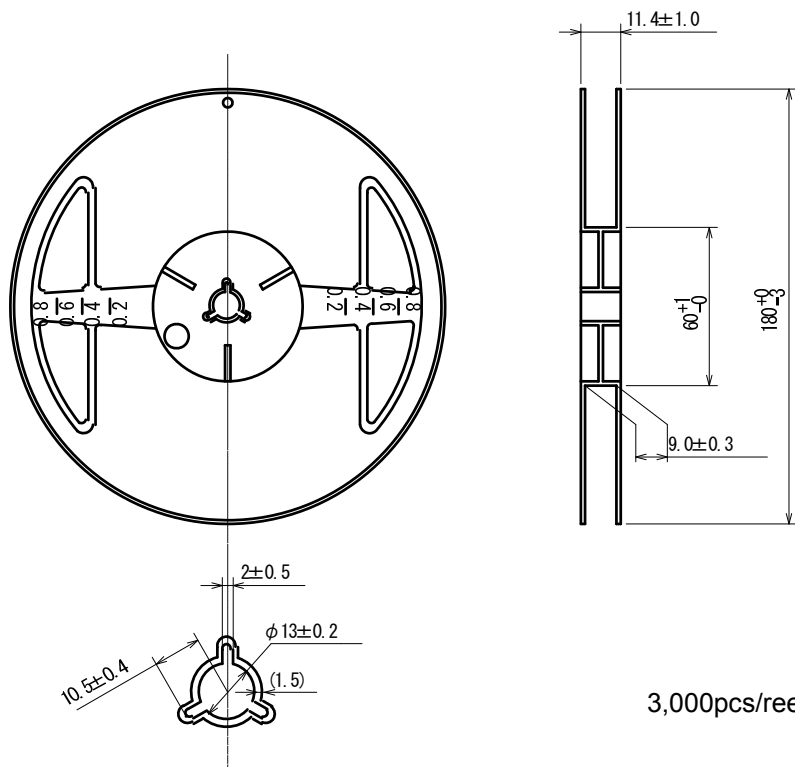


テーピング仕様 / Taping Specifications

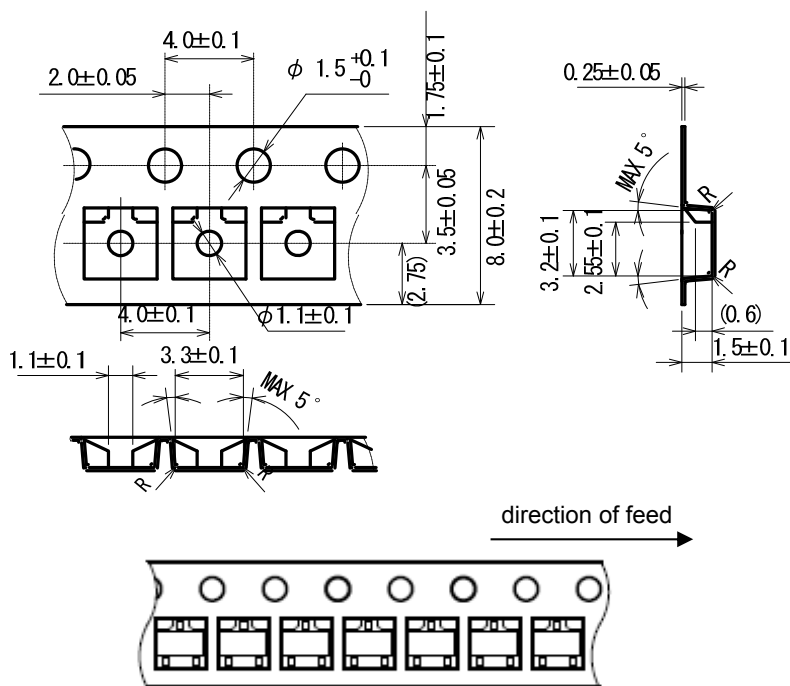
SOT-23

Unit: mm

●リール/Reel



●テーピング仕様/Taping Specifications



R Type : [Device orientation : Right]

Standard feed

●SOT-23 Power Dissipation

Power dissipation data for the SOT-23 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40×40mm (1600mm² in one side)

Copper (Cu) traces occupy 50% of the board area

In top and back faces

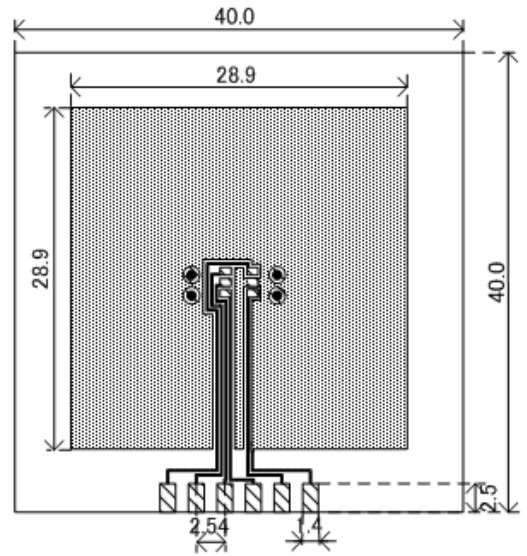
Package heat-sink is tied to the copper traces

(Board of SOT-26 is used)

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

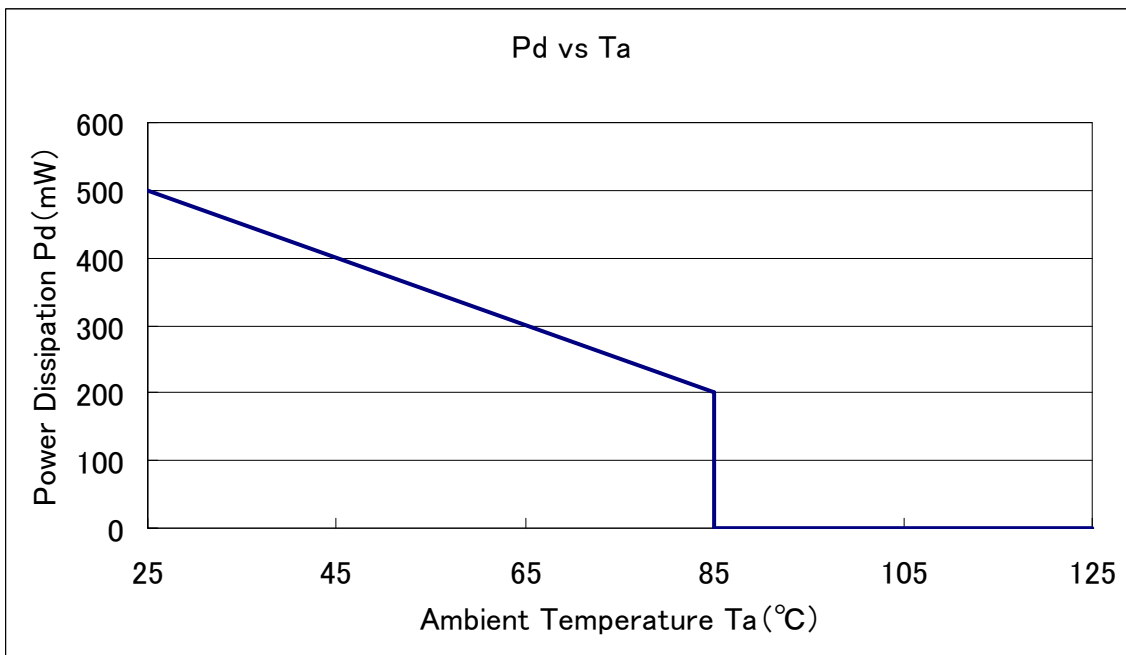
Through-hole : 4 x 0.8 Diameter



2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	



•SOT-23 Power Dissipation (Tj=150°C)

MOSFET DATA

Power dissipation data for the SOT-23 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

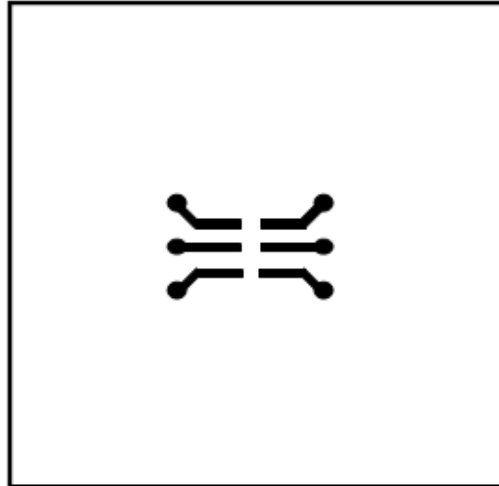
Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 250mm²

Material : Ceramic

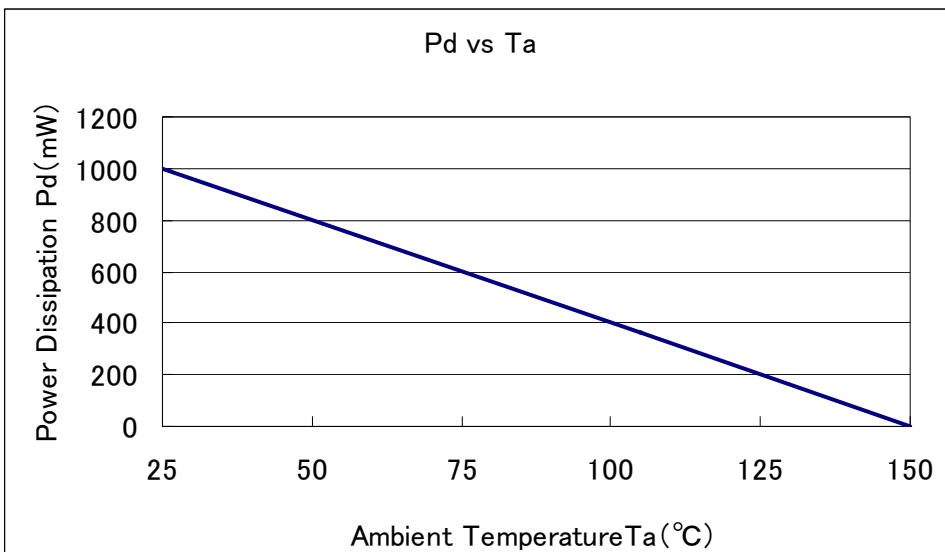
Thickness : 0.8mm



2. Power Dissipation vs. Ambient temperature

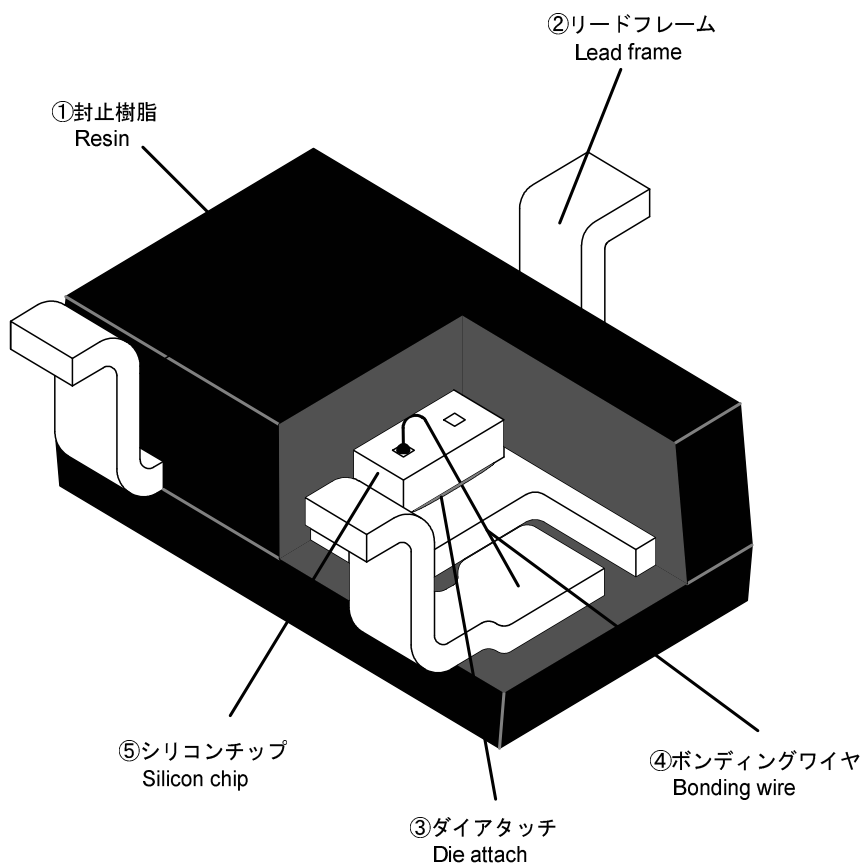
Board Mount (Tjmax=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	125.00
105	360	



SOT-23 構造図 SOT-23 Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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